ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES®	© Co	terial Compo pyright 2005. IPC, Bannoc nternational and Pan-Ameri	kburn, Illinois	. All rights reserv	tion with lower		the decla	aration enc	ompasses all lo	wer level mate	erials for wh	e: if the item is an assemb ich the manufacturer ha this declaration.			
1752-2 1.1		Web Site for Informat		-1752 Standa	Ird	Form Typ Distribute		Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Informa							
Supplier Information															
Company Name *		Company Unique ID		Unique ID Au	uthority	Response Date *			Response Do	cument ID					
SEMTECH CORPORATION		SEMTECH CORPOR	RATION			2012-06-27									
Contact Name *		Title - Contact		Phone - Con	tact *	Email - Cor	ntact *				A (1 -				
ROYA READER		QUALITY ASSURAN	ICE CUST	805-389-274	2	rreader@semtech.com			Duplica	te Contact	-> Authorize	ed Representative			
Authorized Representative * Title - Repres			Э	Phone - Rep	resentative *	Email - Representative *			Supplier Comments or URL for Additional Information						
ROYA READER		QUALITY ASSURA	ICE CUST	805-389-274	2	rreader@semtech.com									
Requester Item Numbe	r	Mfr Item Number		Mfr Item Name)	Effective Date	e Vers	sion Manu	acturing Site Weight *		UOM	Unit Type			
		EClamp2515K.TCT		ESD Protection	on Device for T-Fla	1 China			7.067		mg	Each			
Alternate Recommenda	ation					Alternate Item Co			Comments						
Manufacturing Proces	ss In	formation													
Terminal Plating / Grid Array	Mater	ial	Terminal B	ase Alloy	J-STD-020 MSL Ra	ting Peak	Process	Body Temp	erature Max Tim	ne at Peak Tem	perature Nu	mber of Reflow Cycles			
Nickel/Palladium/Gold (Ni/Pd/Au) CU Allo			CU Alloy	,	1	260 (c	30 se	econds 3				
Comments EClamp2515K.TCT is RI	EACH	I-compliant product	, per EU R	egulation EC	C1907/2006 to inc	lude recent	additio	n of SVHC	candidate lis	t of substand	ces in June	2012			

Save the fields in this form to a file	Evport Data	Import fields from a file into this form	Import Data	Clear all of the fields on this form	Reset Form	Lock the fields on this form to prevent chan	Look Cupplier Fields				
RoHS Material Composition Declaration Declaration Type * Detailed											
		ty limit of 0.1% by mass (100 Ethers (PBDE) and quantity					ominated Biphenyls (PBB),				
chromium, polybromina excess of an applicable gathered the information Company will rely on thi completing this form, ar certifications regarding conditions of that agree	ted biphenyls and/or polybrominate quantity limit, please indicate below it provides in this form using app s certification in determining the co d that Supplier may not have inde heir contributions to the part, and ment, including any warranty rights	ompliance of its products with European pendently verified such information. Ho those certifications are at least as comp	ricted substance?) in excess believe may apply. If the p y and that such information n Union member state laws owever, in situations where prehensive as the certificati hat agreement, will be the s	ss of the applicable quantity lim part is an assembly with lower I is true and correct to the best of that implement the RoHS Dire Supplier has not independently ion in this paragraph. If the Co sole and exclusive source of the	it identified above. If a homoge evel components, the declaration of its knowledge and belief, as of ctive. Company acknowledges y verified information provided lo popany and the Supplier enter is a Supplier?s liability and the Co	eneous material within the part cor on shall encompass all such comp of the date that Supplier complete: s that Supplier may have relied on by others, Supplier agrees that, at into a written agreement with resp impany?s remedies for issues that	ntains a RoHS restricted substance in ponents. Supplier certifies that it s this form. Supplier acknowledges that information provided by others in a minimum, its suppliers have provided				
RoHS Declaration	n * 1 - Item(s) does not conta	ain RoHS restricted substances per the	he definition above			Supplier Acceptance *	Accepted				
	e declared item does not co all applicable exemptions.	ntain RoHS restricted substanc	es per the definition a	above except for defined	RoHS exemptions, then	select the corresponding re	esponse in the RoHS Declaration				
Declaration S	ignature										
In a family of the second	ward a factor and the factor of the second s	al Calaba and all manages of the last		a second se	• • • • •	and the second s	terrestring and - Distingthe stars				

Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.

Supplier Digital Signature

Homogeneous Material Composition Declaration for Electronic Products

Subltem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Line Functions: +I Inserts a New Item /SubItem +M Inserts a new Material +C Inserts a new Substance Category +S Inserts a new Substance - Deletes the element line

	Item/SubItem		Homogeneous	Weight	Unit of		Level	avol	Substance Category			Substance	CAS	Exempt	Weight	Unit of	Tolerance		PPM
	Name		Material	weight	Measure		Le	evei	Substance Category			Substance	CAS	Exempt	weight	Measure	-	+	FEIM
+I -I	Die	+M -M	Doped Silicon	0.1708	mg	+C -	CSup	pplier		+S	-S	Si	7440-21-3		0.1708	mg		2	24,171
+ -	Lead frame	+M -M	C7025	2.49385	img	+C -	C Sup	pplier		+S	-S	Cu	7440-50-8		2.3916	mg			338,40
										+S	-s	Si	7440-21-3		0.0181	mg		:	2,558
						+C -	Св		Nickel (external applic	+S	-s	Nickel	7440-02-0		0.0798	mg			11,292
						+C -	CSu	pplier		+S	-s	Mg	7439-95-4		0.0044	mg		(618
		+M -M	Ni/Pd/Au plating	0.06394	img	+C -	Св			+S	-s	Nickel	7440-02-0		0.0577	mg		1	8,159
			•			+C -	C Su	pplier	middle plating	+S	-s	Pd	7440-05-3		0.0052	mg		7	742
						+C -	C Su	pplier	outer plating	+S	-s	Au	7440-57-5		0.001	mg			147
+ -	Bonding wire	+M -M	Gold wire	0.1418	mg	+C -	C Sup	pplier		+S	-S	Au	7440-57-5		0.1418	mg		2	20,061
+ -	Molding compound	+M -M	EME-G770HCD	4.16341	img	+C -	C Sup	pplier		+S	-S	Silica fused	60676-86-0		3.8928	mg		į	550,81
			-							+S	-s	Epoxy resin	Proprietary		0.1249	mg			17,673
										+S	-s	Phenol resin	Proprietary		0.1249	mg			17,673
										+S	-s	Carbon black	1333-86-4		0.0208	mg			2,946
+ -	Die attached Epoxy	+M -M	8006NS	0.033552	mg	+C -	C Sup	pplier		+S	-S	Treated silica	Proprietary		0.0027	mg		3	380
	-									+S	-s	Glycol ethers	Proprietary		0.0067	mg		9	949
										+S	-s	Metal oxide	Proprietary		0.0094	mg			1,329
										+S	-s	Curing agent & Hardene	Proprietary		0.0027	mg			380
										+S	-s	epoxy resins	Proprietary		0.0121	mg			1,709